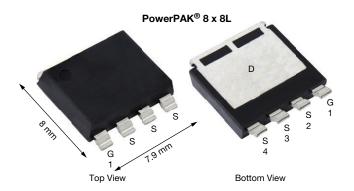


www.vishay.com

Vishay Siliconix

Automotive N-Channel 40 V (D-S) 175 °C MOSFET

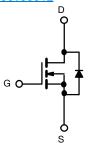


PRODUCT SUMMARY				
V _{DS} (V)	40			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.00124			
I _D (A)	460			
Configuration	Single			
Package	PowerPAK 8 x 8L			

FEATURES

- TrenchFET® Gen IV power MOSFET
- AEC-Q101 qualified
- 100 % R_q and UIS tested
- Thin 1.6 mm package
- · Very low thermal resistance
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





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ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-source voltage		V_{DS}	40	V		
Gate-source voltage		V_{GS}	± 20	V		
Continuous drain current	T _C = 25 °C	I _D	460			
	T _C = 125 °C		265			
Continuous source current (diode conduction)		I _S	450	Α		
Pulsed drain current ^b		I _{DM}	900			
Single pulse avalanche current	L = 0.1 mH	I _{AS}	48			
Single pulse avalanche energy	L = U.T IIII	E _{AS}	115.2	mJ		
Maximum power dissipation	T _C = 25 °C	P _D	500	W		
	T _C = 125 °C	P _D	166			
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	°C		
Soldering recommendations (peak temperature) ^d			260	C		

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-ambient PC	CB mount c	R _{thJA}	44	°C/W	
Junction-to-case (drain)		R_{thJC}	0.3	C/VV	

Notes

- a. Package limited
- b. Pulse test; pulse width $\leq 300~\mu\text{s},$ duty cycle $\leq 2~\%$
- c. When mounted on 1" square PCB (FR4 material)
- d. See solder profile (www.vishay.com/doc?73257). The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection



Vishay Siliconix

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static					•			
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0$, $I_D = 250 \mu A$		40	-	-	V	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2	3	3.5	V	
Gate-source leakage	I _{GSS}	V _{DS} =	0 V, V _{GS} = ± 20 V	-	-	± 100	nA	
Zero gate voltage drain current		$V_{GS} = 0 V$	V _{DS} = 40 V	-	-	1		
	I _{DSS}	V _{GS} = 0 V	V _{DS} = 40 V, T _J = 125 °C	-	-	200	μA	
		V _{GS} = 0 V	V _{DS} = 40 V, T _J = 175 °C	-	-	330		
On-state drain current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 V$	100	-	-	Α	
Drain-source on-state resistance ^a		V _{GS} = 10 V	I _D = 20 A	-	0.00100	0.00124	Ω	
	R _{DS(on)}	V _{GS} = 10 V	I _D = 20 A, T _J = 125 °C	-	-	0.00200		
		V _{GS} = 10 V	I _D = 20 A, T _J = 175 °C	-	-	0.00240		
Forward transconductance b	9 _{fs}	V _{DS} = 15 V, I _D = 60 A		-	150	-	S	
Dynamic ^b								
Input capacitance	C _{iss}		0 V V _{DS} = 25 V, f = 1 MHz	-	5360	6975	pF	
Output capacitance	C _{oss}	$V_{GS} = 0 V$		-	2070	2700		
Reverse transfer capacitance	C _{rss}			-	167	215		
Total gate charge ^c	Qg			-	92	130		
Gate-source charge c	Q_{gs}	V _{GS} = 10 V	$V_{DS} = 20 \text{ V}, I_{D} = 20 \text{ A}$	-	26	-	nC	
Gate-drain charge ^c	Q_{gd}				20.1	-	1	
Gate resistance	R_g	f = 1 MHz		0.65	1.59	2.56	Ω	
Turn-on delay time c	t _{d(on)}			-	18.5	26		
Rise time ^c	t _r	$V_{DD} = 20 \text{ V, } R_L = 1 \Omega$ $I_D \cong 20 \text{ A, } V_{GEN} = 10 \text{ V, } R_g = 1 \Omega$		-	18	25	ns ns	
Turn-off delay time ^c	t _{d(off)}			-	37	52		
Fall time ^c	t _f			-	14	20		
Source-Drain Diode Ratings and Cha	racteristics b							
Reverse recovery time	t _{rr}	V _{DD} = 32 V, I _{FM} = 15 A, di/dt = 100 A/μs		-	59	-	ns	
Reverse recovery charge	Q _{rr}			-	69	-	nC	
Reverse recovery current	I _{RM}			-	2	3.2	Α	
Pulsed current a	I _{SM}			-	-	900	Α	
		I _F = 50 A, V _{GS} = 0						

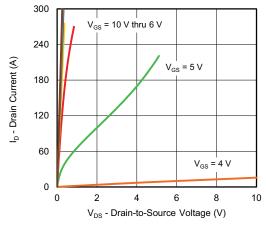
Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

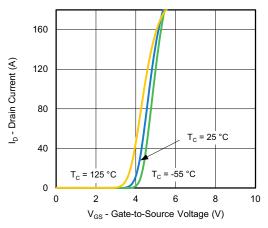
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



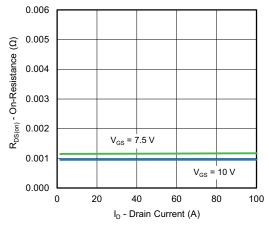
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



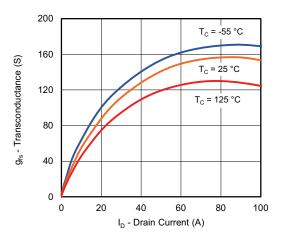
Output Characteristics



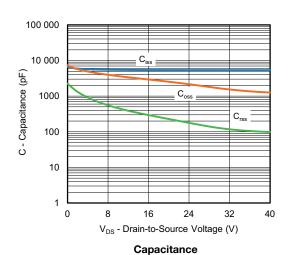
Transfer Characteristics

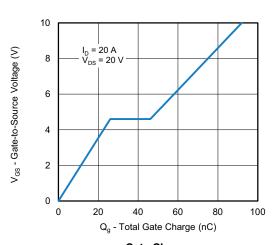


On-Resistance vs. Drain Current



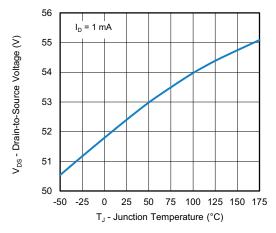
Transconductance



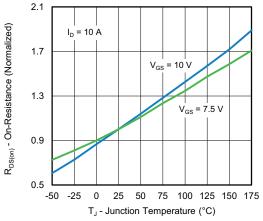




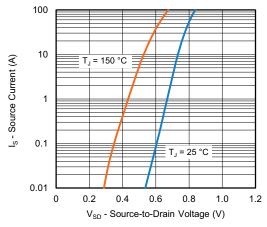
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



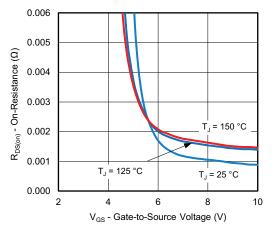
Drain Source Breakdown vs. Junction Temperature



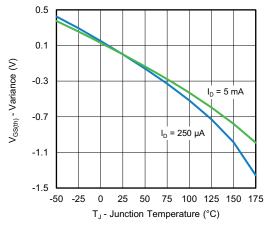
On-Resistance vs. Junction Temperature



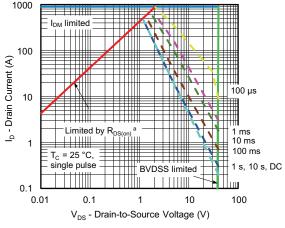
Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Safe Operating Area

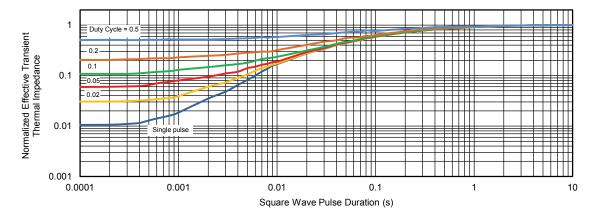
Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

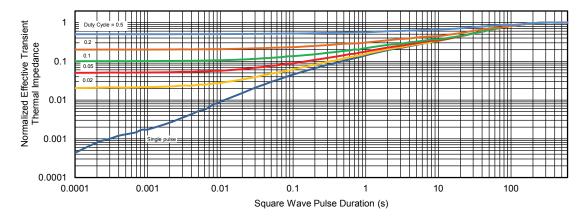
For technical questions, contact: automostech



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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